



## **Revasum ships first 6EZ Silicon Carbide Polisher for Customer Evaluation**

**San Luis Obispo, California - 25 November 2020:** Global semiconductor technology and equipment firm **Revasum, Inc. (ASX: RVS, 'Revasum' or the 'Company')** is pleased to announce the first shipment of its new flagship 6EZ Silicon Carbide (SiC) Wafer Polisher to a major global semiconductor wafer manufacturer for customer evaluation. The polisher is being shipped domestically to the customer's US location.

### **Highlights**

- Revasum ships first 6EZ Silicon Carbide (SiC) Wafer Polisher ("6EZ") to major global semiconductor wafer manufacturer for a 6-month evaluation program. The polisher has shipped today to the manufacturer's US location.
- Customer evaluation represents the next major step in the commercialization of the 6EZ.
- The 6EZ Silicon Carbide Polisher, alongside the 7AF-HMG Silicon Carbide Grinder, provides Revasum's customers with an optimized, fully automated single-wafer grind and polish toolset.
- The Company is one of only two globally with this technology.
- The 6EZ is easily configured to polish 150mm or 200mm SiC wafers, which enables maximum flexibility in addressing both increased global demand for 150mm wafers and the anticipated production ramp of 200mm wafers in the near future.
- Compared to traditional silicon devices, SiC devices have superior physical and electronic properties for high voltage and high power in 5G, electric vehicle (EV) and power device applications.
- Revasum is in ongoing discussions regarding product sales with global SiC wafer manufacturers and device makers.

### **Shipment of first 6EZ Silicon Carbide Polisher for Evaluation Program**

The 6EZ SiC Wafer Polisher (6EZ), the Company's new flagship product, will now undergo six months of trial and evaluation at a customer site in the United States.

The 6-month evaluation period is industry standard for a new tool, and is the next major step to achieving commercialization of the 6EZ. The customer has no commitment to place a purchase order at this point in time, but the Company is confident that the tool will meet the required technical specifications during the evaluation period.

Revasum's Chief Technology Officer, Dr. Robert Rhoades, said: "The customer trial and evaluation program for our 6EZ Silicon Carbide Wafer Polisher is an important milestone for the Company and represents a major step towards commercialization and future sales of this significant new polisher technology. This innovative technology and design are a culmination of years of work and we believe will represent the flagship polisher for the silicon carbide industry.

"Silicon carbide demand is growing exponentially around the globe, and we are ready to capitalize on this trend. We are leading the market for silicon carbide grinding and polishing technology, particularly in the 200mm wafer size segment, which is seeing a huge uptick in demand driven by multiple industries and end uses.

"We are currently in discussions regarding product sales with multiple global SiC wafer manufacturers and device makers," said Dr. Rhoades.



Revasum CFO Rebecca Shooter-Dodd, said: “We’ve launched the 6EZ tool to market at an optimum time to meet growing demand for SiC wafers globally and we expect significant interest in this product. It confirms Revasum as a global market leader and innovator in this space and being early to market with this product is a testament to the depth of our IP and capabilities within our team.”

### **SiC Market Update & Product Information**

Following several decades of development, commercial SiC diodes and transistors are delivering substantially improved performance with lower internal losses at high voltages with high powers and high frequencies compared to available devices made from silicon. Sales in the industry are now rising fast, with demand outpacing supply, as SiC devices are deployed in the automotive, Internet of Things (IoT), power regulation and 5G markets. Given the high level of demand for SiC substrates, it is essential to manufacture these wafers in the most efficient manner.

As the SiC industry moves to larger wafer sizes, the net throughput advantage of batch processing diminishes. This is due to fewer wafers fitting within the fixed platen surface area of any given polisher. For example, a typical batch tool that holds 30 wafers with a diameter of 100mm wafers can only accommodate a batch size of twelve (12) for 150mm wafers, and just nine (9) for 200mm wafers. As a result, the greatest asset of the batch approach – parallel processing of many wafers – is rapidly being eroded by simple geometry.

Replacing batch lapping and polishing with a single-wafer automated grinder and polisher also enables scalability in SiC substrate production while improving consistency, increasing yield and lowering the manufacturing cost. Single-wafer processing can also reduce the number of labour hours needed to support any given production volume. There are fewer operations in the overall process sequence, the manual loading and unloading for each batch tool is eliminated, and there is no longer the need to sort wafers into thickness-matched batches, this reducing the reliance on in-line data measurements.

Revasum already has a strong customer base for its 7AF-HMG Silicon Carbide grinder. The 7AF-HMG, alongside the 6EZ Silicon Carbide Polisher, provides Revasum’s customers with an optimized, fully automated single-wafer grind and polish toolset. The 7AF-HMG and 6EZ are also designed to be easily converted between 150mm or 200mm wafers.

The 6EZ can function without operator intervention to sequentially polish and clean both surfaces of fifty (50) SiC wafers.

Revasum’s 6EZ technology enables more effective single wafer SiC polishing as a result of:

- Fully automated dry-in/ dry-out technology
- Better wafer-to-wafer consistency
- Improved TTV and surface finish
- No requirement for wafer sort
- Virtually no wafer rework required
- Lower risk of scrap
- Higher yield

*THIS ANNOUNCEMENT IS AUTHORIZED FOR RELEASE BY THE BOARD OF DIRECTORS*

**--ENDS--**

#### **Company Contact/Investor Relations**

Rebecca Shooter-Dodd  
Chief Financial Officer  
[rebecca.shooter-dodd@revasum.com](mailto:rebecca.shooter-dodd@revasum.com)  
+1 (805) 541-6424

#### **Media Contact**

Jane Munday  
FTI Consulting  
[jane.munday@fticonsulting.com.au](mailto:jane.munday@fticonsulting.com.au)  
+61 400 400 248



### **Safe Harbor Statement**

This announcement contains forward-looking statements, which address a variety of subjects including, for example, financial projections, our statements regarding expected events, including expected revenue and earnings, system shipments, expected product offerings, product development, market adoption and technical advances. Statements that are not historical facts, including statements about our beliefs, plans and expectations, are forward-looking statements. Such statements are based on our current expectations and information currently available to management and are subject to a number of factors and uncertainties, many of which are outside the control of the Company, which could cause actual results to differ materially from those described in the forward-looking statements. The Company's management believes that these forward-looking statements are reasonable as and when made. However, you should not place undue reliance on any such forward-looking statements because such statements speak only as of the date they are made. Revasum does not undertake any obligation to publicly update or revise any forward-looking statements, whether as a result of new information, future events or otherwise, except as required by law or the ASX Listing Rules. In addition, forward-looking statements are subject to certain risks and uncertainties that could cause actual results, events and developments to differ materially from our historical experience and our present expectations or projections.

### **About Revasum, Inc. (ASX: RVS)**

Revasum, Inc. (ARBN: 629 268 533) specializes in the design and manufacturing of equipment used for the global semiconductor industry. Revasum's technology and equipment assists in the advancement of technology for a wide range of markets and applications including automotive, IoT, 5G, telecommunications, electrification and power devices. Revasum's product portfolio includes equipment for grinding, polishing, and chemical mechanical planarization processes used to manufacture devices for key end markets. Its flagship 6EZ Silicon Carbide (SiC) Wafer Polisher is the world's first fully automated single SiC wafer polisher. Revasum's tools, including the 6EZ SiC polisher, are uniquely positioned to meet the growing global demand, maximizing quality and efficiency. Revasum's equipment is designed and developed in close collaboration with its customers. [www.revasum.com](http://www.revasum.com)